

RZ/T2H

Program Writing Guide

Introduction

This document describes how to build the program that runs on the RZ/T2H Evaluation Board and how to write the program to the serial flash memory.

This document presents a guide to writing for the following sample program.

r01an7333XX0100-rzt2h-motor-control.zip

./workspace/RZT2H_INVBLV_SPM_ENCD_FOC_ **E2S**_V100 (e² studio)

./workspace/RZT2H_INVBLV_SPM_ENCD_FOC_ **EWARM**_V100 (IAR Embedded Workbench for Arm)

Target Device

RZ/T2H (R9A09G077M44GBG)

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1. Overview

1.1 Hardware Configuration

Figure 1-1 shows the hardware connection configuration and Table 1-1 lists the equipment to be connected.

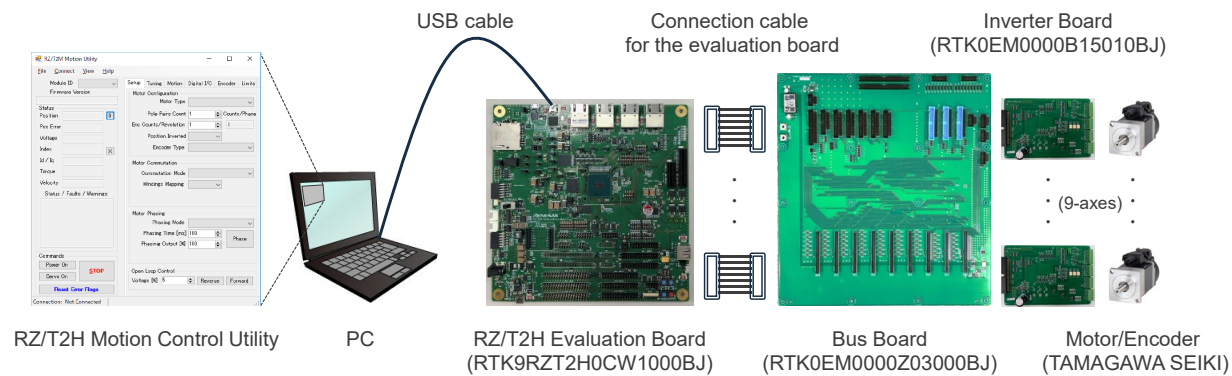


Figure 1-1 Hardware Configuration (Connection Configuration)

Table 1-1 Hardware Configuration (Connection Equipment)

Equipment	Model name
RZ/T2H Evaluation Board	RTK9RZT2H0CW1000BJ
MPU	R9A09G077M44GBG 729-pin FCBGA, RAM 2[MB]
On-board memory	OctaFlash: 64[MB]
Operating frequency	Cortex-R52 CPU0: 1000[MHz] Cortex-R52 CPU1 and Cortex-A55 are unused.
Operating voltage	DC 15[V]/3[A], 15[V]/3[A]
Operating mode	xSPI0 boot mode (x1 boot serial flash)
Bus Board	RTK0EM0000Z03000BJ
Inverter Board	RTK0EM0000B15010BJ
Operating voltage	DC 24[V]
Motor /Encoder (manufactured by TAMAGAWA SEIKI)	TSM3101N2001E020 /TS5669N124 (FA-CODER®)

1.2 Software Configuration

Table 1-2 shows the software development environment and Table 1-3 shows the tool to support development.

Table 1-2 Software Configuration (Development Environment)

Integrated Development Environment (IDE)	e ² studio	IAR Embedded Workbench for Arm
IDE version	2024-10	9.60.2 + patch (EWARM patch for RZ/T2H Rev.1.0)
FSP version	2.2.0	FSP Smart Configurator 2024-10
Toolchain version	GNU Arm Embedded 12.2.1.arm-12-24	-
In Circuit Emulator (ICE)	J-Link OB	IAR I-jet

Table 1-3 Software Configuration (Tool to Support Development)

Tool name	Tool version
RZ/T2H Motion Control Utility	1.0.0.0

2. How to Build and Write the Program

2.1 e² studio

2.1.1 Unzip the Sample Program

Unzip the following sample program to any folder.

The path should be only half-width alphanumeric characters and underscores.

```
r01an7333XX0100-rzt2h-motor-control.zip  
./workspace/RZT2H_INVBLV_SPM_ENCD_FOC_E2S_V100
```

2.1.2 Launch the IDE

Launch e² studio from the Windows start menu.

Specify the workspace directory (./workspace) and click the [Launch] button.

2.1.3 Import Existing Project

Select [Import] from the [File] menu to open the Import dialog box.

Select [Existing Projects into Workspace] from [General] and click the [Next] button.

Select the root directory (project folder) from the [Browse] button and click the [Finish] button.

2.1.4 Build the Project

Select [Build All] from the [Project] menu to build the project.

If the build is successful, the message "Build Finished" will be displayed in the [Console].

2.1.5 Download (Debugging)

Click the  button to start debugging.

This operation writes the program to the serial flash memory.

If the download is complete, the message "Finished download" will be displayed in the [Console].

Click the  button to terminate debugging.

2.2 IAR Embedded Workbench for Arm

2.2.1 Unzip the Sample Program

Unzip the following sample program to any folder.

The path should be only half-width alphanumeric characters and underscores.

r01an7333XX0100-rzt2h-motor-control.zip

./workspace/RZT2H_INVBLV_SPM_ENCD_FOC_ewarm_V100

2.2.2 Launch the IDE

Double-click the workspace file (*.eww) in the project folder to launch IAR Embedded Workbench for Arm.

2.2.3 Build the Project

Select [Rebuild All] from the [Project] menu to build the project.

If the build is successful, the message "Build succeeded" will be displayed in the [Build] window.

2.2.4 Download

Select the [Download] > [Download active application] from the [Project] menu to write the program to the serial flash memory.

3. Operation Confirmation

Remove the ICE from RZ/T2H Evaluation Board and start up standalone.

Operate the RZ/T2H Motion Control Utility and check that the motor rotates.

For details, see "RZ/T2H Startup Manual (RZ/T2H Motion Control Utility) (R01AN7334)".

4. Reference Documents

- RZ/T2H Startup Manual (RZ/T2H Motion Control Utility) (R01AN7334)
- RZ/T2H Vector Control for Permanent Magnetic Synchronous Motor with Encoder (9-axes)
- Absolute Encoder (R01AN7333)
- e² studio Integrated Development Environment User's Manual: Getting Started Guide RZ Family
(R20UT4535)

Revision History

Rev.	Date	Description	
		Page	Summary
1.0	2024.11.26	-	First edition issued

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

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Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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